

Customer No.: 31561
Application No.: 10/063,573
Docket No.: 08385-US-PA

Abstract Amendment

Please amend the abstract as follow:

A method of forming bumps on the active surface of a silicon wafer. An under-ball metallic layer is formed over the active surface of the wafer. A plurality of first solder blocks is attached to the upper surface of the under-ball metallic layer. Each first solder block has an upper surface and a lower surface. The lower surface of each first solder block bonds with the under-ball metallic layer. The upper surfaces of the first solder blocks are planarized. A second solder block is attached to the upper surface of each first solder block and then a ~~reflow~~reflow operation is carried out.